



Material Content Data Sheet



Halogen-Free

Sales Product Name	IAUT300N10S5N014	Issued	23. June 2021
MA#	MA005430880		
Package	PG-HSOF-8-1	Weight*	777.30 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.727	0.99	0.99	9941	9941
leadframe	inorganic material	phosphorus	7723-14-0	0.126	0.02		162	
	non noble metal	iron	7439-89-6	0.421	0.05		541	
	non noble metal	copper	7440-50-8	420.040	54.04	54.11	540385	541088
wire	non noble metal	aluminium	7429-90-5	19.989	2.57	2.57	25716	25716
encapsulation	inorganic material	zinc oxide	1314-13-2	3.157	0.41		4062	
	miscellaneous	miscellaneous	-	12.629	1.62		16248	
	plastics	epoxy resin	-	47.360	6.09		60929	
	inorganic material	silicon dioxide	60676-86-0	252.587	32.50	40.62	324956	406195
lead finish	non noble metal	tin	7440-31-5	6.479	0.83	0.83	8335	8335
plating	inorganic material	phosphorus	7723-14-0	0.001			2	
	non noble metal	nickel	7440-02-0	0.526	0.07	0.07	677	679
solder	non noble metal	tin	7440-31-5	0.125	0.02		161	
	noble metal	silver	7440-22-4	0.156	0.02		201	
	non noble metal	lead	7439-92-1	5.973	0.77	0.81	7684	8046
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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